

ON Semiconductor			9/9/2019	
Base Part		FCMT250N65S3	HF	
Orderable Part		FCMT250N65S3	Total weight (mg)	156.0655
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	8.46	Silicon (Si)	7440-21-3	100
Die Attach Solder	5.135	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	27.5725	Silver (Ag)	7440-22-4	0.02248617
		Tin (Sn)	7440-31-5	13.41916765
		Zinc (Zn)	7440-66-6	0.09538489
		Iron (Fe)	7439-89-6	1.95847312
		Copper (Cu)	7440-50-8	84.50448817
Mold Compound-Black	112.99	Ortho Cresol Novolac Resin	29690-82-2	9.02734755
		Carbon Black (C)	1333-86-4	1.0000885
		Fused Silica (SiO2)	60676-86-0	87.97238694
		Phenolic Resin (Novolac)	9003-35-4	2.00017701
Wire Bond - Al	1.69	Aluminum (Al)	7429-90-5	100
Wire Bond - Cu	0.218	Copper (Cu)	7440-50-8	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				